## 506185833 08/03/2020

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
WEI-AN LAI	07/13/2020
SHIH-WEI PENG	07/15/2020
WEI-CHENG LIN	07/13/2020
JIANN-TYNG TZENG	07/13/2020

### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16933570

### **CORRESPONDENCE DATA**

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DATE SIGNED:	08/03/2020

**Total Attachments: 1** 

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PATENT REEL: 053388 FRAME: 0377

506185833

7 (S) NP-3/595-0-06-8/ Docket No. T5057-1503

P20201161US00

## ASSIGNMENT

In consideration of the premises and	ther good and valuable	a consideration in ha	and paid, the rece	sipt and sufficiency of
which is hereby acknowledged, the undersigned	•		•	•

1) Wei-An LAI

RECORDED: 08/03/2020

3) Wei-Cheng LIN

2) Shih-Wei PENG

4) Jiann-Tyng TZENG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto <u>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY</u>, LTD. having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C. and

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

# LAYOUT DESIGNS OF INTEGRATED CIRCUITS HAVING BACKSIDE ROUTING TRACKS

(a)	for which an application for United States Letters Patent was filed on 2020-07-20, and identified by United States Patent Application No. 16/933,570; or
(b)	for which an application for United States Letters Patent was executed on,
all Unite continua Property	undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and ed States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or ations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned nat the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

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PATENT REEL: 053388 FRAME: 0378